

ABSTRACT

A curable resin film is a film for forming a first protective film on a surface having a bump of a semiconductor wafer by being attached to the surface, and being
5 cured, in which a visible light transmittance of the curable resin film before curing is 45% or less, and an infrared transmittance of the curable resin film before curing is 33% or more. A sheet for forming a first protective film includes a first supporting sheet, and the curable resin film on one surface of the first supporting sheet.

10 Fig. 2